

FORM PTO-1449 (Modified)
U.S. Department of Commerce, Patent and Trademark Office

Docket No.

02-5624

Serial No.

W/676934

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

Applicants

Byung-Sung Kwak et al.

Filing Date
HerewithGroup
~~Unknown~~ 2823

U.S. Patent Documents

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
WP	AA	5,874,367	2/23/99	Dobson	438	787	
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

Foreign Patent Documents

Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

WP	AR	Bothra, S., et al., "Integration of 0.25 μ m Three and Five Level Interconnect System for High Performance ASIC", <u>1997 Proceedings Fourteenth International VMIC Conference</u> , Santa Clara, CA, June 10-12, 1997, pp.43-48.
WP	AS	Brongersma, S.H., et al., 'Non-Correlated Behavior of Sheet Resistance and Stress During Self-Annealing of Electroplated Copper', <u>IITC</u> , 1999, pp.290-292.
WP	AT	Dobson, C.D., et al., "Advanced SiO ₂ Planarization Using Silane and H ₂ O ₂ ", <u>Semiconductor International</u> , December 1994, pp. 85-88.

Examiner

John H. H. H.

Date Considered

9/27/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

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	BB						
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	BD						
	BE						
	BF						
	BG						
	BH						
	BI						
	BJ						
	BK						

Foreign Patent Documents

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	BL							
	BM							
	BN							
	BO							
	BP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TVP	BR	Hau-Riege, Stefan P., Handbook entitled "Copper Interconnect Technology", University of California-Berkeley Extension Course, April, 2002, pp. 129-137.
TVP	BS	Kittel, Charles, <u>Introduction to Solid State Physics</u> , 6th ed., New York: John Wiley & Sons, 1986, pp. 143, 145.
TVP	BT	McClatchie, S., et al., "Low Dielectric Constant Oxide Films Deposited Using CVD Techniques", <u>1998 Proceedings Fourth International DUMIC Conference</u> , February 16-17, 1998, pp. 311-318.

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	CA						
	CB						
	CC						
	CD						
	CE						
	CF						
	CG						
	CH						
	CI						
	CJ						
	CK						

Foreign Patent Documents

Translation

		Document Number	Date	Country	Class	Subclass	Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TVP	CR	Peters, Laura, "Low-k Dielectrics: Will Spin-On or CVD Prevail?", <u>Semiconductor International</u> , Vol. 23, No. 6, June, 2000, pp. 108-110, 114, 116, 118, 122, and 124.
TVP	CS	Peters, Laura, "Pursuing the Perfect Low-k Dielectric", <u>Semiconductor International</u> , Vol. 21, No. 10, September, 1998, pp. 64-66, 68, 70, 72, and 74.
TVP	CT	Ramanan, V.R.V., et al., "Crystallization Kinetics in Fe-B-Si Metallic Glasses", <u>J. Appl. Phys.</u> , Vol. 53, No. 3, March, 1982, pp. 2273-2275.

Examiner

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9/27/07

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	DA						
	DB						
	DC						
	DD						
	DE						
	DF						
	DG						
	DH						
	DI						
	DJ						
	DK						

Foreign Patent Documents

Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	DL							
	DM							
	DN							
	DO							
	DP							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

wp	DR	Ritzdorf, T., et al., "Comparative Investigation of Plating Conditions on Self-Annealing of Electrochemically Deposited Copper Films", <u>IITC</u> , 1999, pp. 287-289.
wp	DS	Rossnagel, S.M., et al., "From PVD to CVD to ALD for Interconnects and Related Applications", <u>IITC</u> , 2001, p. 2.
	DT	

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